



Рb паяльная паста

SH-6309RMA

Rev. 2016/03/01 Ver. 02-01

ОБЗОР



Sn63Pb37 Припой
Низкое содержание галогенов
Не требует отмывки
Исключает образования пустот

ПРИМЕНЕНИЕ

Универсальная паяльная паста со свинцом
Широкий диапазон применения

ТЕХНИЧЕСКИЕ ХАРАКТЕРИСТИКИ

Внешний вид	Серая паста без видимых включений	
Alloy Composition	Sn63/Pb37	JIS-Z-3282
Melting Point	183 °C	DSC
Particle Size	(Type 3) +45µm < 1% , - 20µm < 10% (Type 4) +38µm < 1% , - 20µm < 10%	IPC-TM-650, 2.2.14
Powder Shape	Spherical	
Flux Content	10.0 ± 1.0 wt%	JIS-Z-3197, 6.1.
Halide Content	<0.5 wt% (in flux)	J-STD-004
Viscosity	200 ± 30 Pa.s (25±1°C, 10rpm, Malcom)	JIS-Z-3284 Annex 6
Flux Type	ROL1	J-STD-004

Alloy Detail Composition

(Sn)	(Pb)	(Cu)	(Zn)	(Al)	(Sb)	(Fe)	(As)	(Bi)	(Cd)
63.0 ± 0.5	REM.	0.05 MAX	0.001 MAX	0.001 MAX	0.05 MAX	0.02 MAX	0.03 MAX	0.1 MAX	0.002 MAX

(wt%)

Scan Code for Solder
Paste Documents





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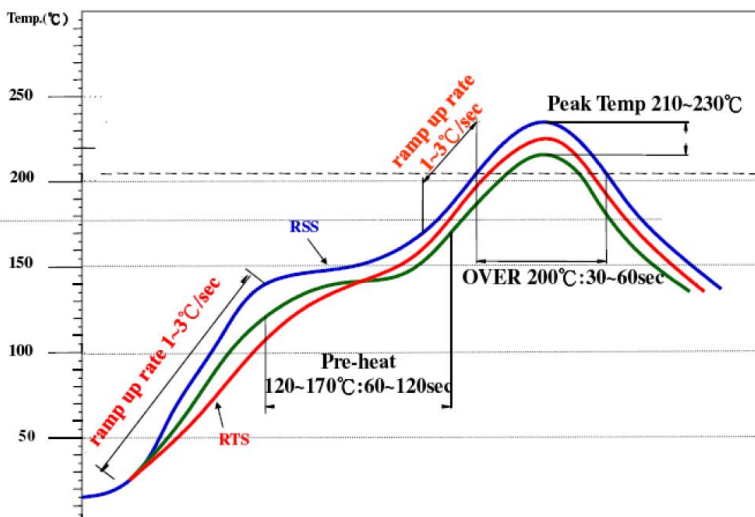
PERFORMANCE & RELIABILITY

Copper Plate Corrosion Test	Pass	JIS-Z-3197, 8.4.1
Spreading Test	> 90%	JIS-Z-3197, 8.3.1.1
Copper Mirror Test	Pass	IPC-TM-650, 2.3.32
Viscosity Test (25°C, 10 rpm)	200 ± 30 Pa.s	JIS-Z-3284, Annex 6
Tackiness Test (gf)	> 120 (8hr)	JIS-Z-3284, Annex 9
Slump Test	Less than 0.3 mm	JIS-Z-3284, Annex 7,8
Solder Ball Test	Pass	JIS-Z-3284, Annex 11

S.I.R. Test ▲	> 1 x 10 ⁹ Ω, Pass	IPC-TM-650, 2.6.3.3
Electro Migration Test ◆	Pass	IPC-TM-650, 2.6.14.1

▲ Test Conditions : 85°C, 85% RH for 168hrs ◆ Test Conditions: 65°C, 85% RH for 596hrs

RECOMMENDED REFLOW PROFILE



Ramp Up Rate (120-170°C):	1.0-3.0 °C/sec
Pre-heating Time (120-170°C):	60-120 sec
Time Period Above 200°C:	30-60 sec
Ramp Up Rate (210-230°C) :	1.0-3.0 °C/sec
Peak Temperature:	210-230 °C
Ramp Down Cooling Rate:	1.0-3.0 °C/sec

Note: The recommended reflow profile is provided as a guideline. Optimal profile may differ due to oven type, assembly layout or other process variables.



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STORAGE & HANDLING:

- Refrigerate the solder paste at 0-10°C. Shelf life is 6 months from production date (sealed package).
- Keep away of direct sunlight.
- Allow the paste to reach defined printing temperature (room temperature) for 3-4 hrs. Do not heat up the solder paste rapidly.
- For jars packaging, mix the solder paste before use for 1-3 mins by plastic spatula.
- It is recommended to finish fresh paste within 24 hrs. Do not store used paste and fresh paste in the same jar.
- If printing process was interrupted for more than 1 hour, remove the remained paste from stencil and seal in the jar.
- Recommended printing environment is 22-28°C and RH 30-60%.

Note: For more information, please refer to solder paste application guideline sheet

HOW TO ORDER

SH-6309 – RMA – T3 – 500

Solder Alloy
SH-6309 = Sn63Pb37

Flux
RMA = ROL1

Particle Size
T3 = 20-45µm
T4 = 20-38µm

Weight / Packaging
30 = syringe 30g
100 = syringe 100g
150 = syringe 150g
250 = plastic jar 250g
500 = plastic jar 500g
600 = small cartridge 600g
1200 = large cartridge 1200g



CONTACTS

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